



Features

Customizable size, thickness and metallization layers

Low impedance at high frequencies

Prevents creep-up of solder and epoxy

Orientation recognizable at a glance

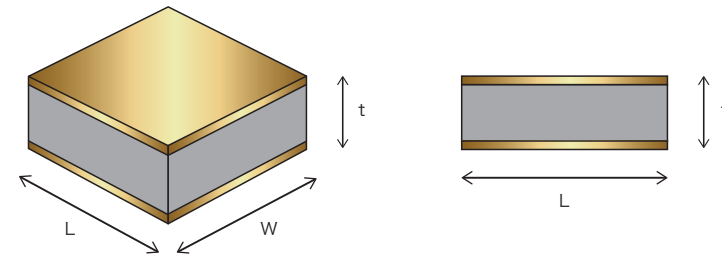
Uses

Height matching to reduce length of wire bonds

Conductive shims used for creating bonding pads

Ground Blocks

Design Guide



Parameter	Design Guide
Length: L	0.25 mm ~ 2.00 mm
Standard Tolerance of Length	±0.05mm
Width: W	0.13 mm ~ 2.00 mm
Standard Tolerance of Width	±0.05mm
Thickness: t	0.08 mm ~ 0.63 mm
Standard Tolerance of thickness	±0.03mm
Metallization (both sides)	Ti - Pt - Au

* Please contact us for other sizes and metallization schemes

Key to Part Numbers

(1)	(2)	(3)	(4)	(5)
P/N: TGB 040 025 008 - B				
(1) Series TGB: Tecdia Ground Block	(3) Width 013: 0.13 mm 025: 0.25 mm 200: 2.00 mm	(5) Packaging - B: Blue Tape Blank: Waffle Pack	(4) Thickness 008: 0.08 mm 025: 0.25 mm 063: 0.63 mm	
(2) Length 025: 0.25 mm 040: 0.40 mm 200: 2.00 mm				

This specification may be modified without notice.(2017.AUG) C-275-3